# **Amplifier Transistor**

## **PNP Silicon**

#### **Features**

• These are Pb-Free Devices\*

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	-60	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	-60	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	-5.0	Vdc
Collector Current - Continuous	I <sub>C</sub>	-600	mAdc
Total Device Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	625 5.0	mW mW/°C
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	1.5 12	W mW/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

#### THERMAL CHARACTERISTICS

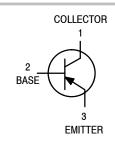
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction to Case	$R_{\theta JC}$	83.3	°C/W

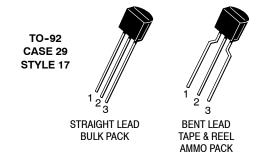
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



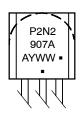
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#### **MARKING DIAGRAM**



A = Assembly Location

Y = Year WW = Work Week ■ = Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
P2N2907AG	TO-92 (Pb-Free)	5000 Units / Bulk
P2N2907ARL1G	TO-92 (Pb-Free)	2000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Charac	teristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS			I	1	l .
Collector-Emitter Breakdown Voltage (Note $(I_C = -10 \text{ mAdc}, I_B = 0)$	1)	V <sub>(BR)CEO</sub>	-60	-	Vdc
Collector-Base Breakdown Voltage (I <sub>C</sub> = -10 μAdc, I <sub>E</sub> = 0)		V <sub>(BR)CBO</sub>	-60	-	Vdc
Emitter-Base Breakdown Voltage ( $I_E = -10 \mu Adc, I_C = 0$ )		V <sub>(BR)EBO</sub>	-5.0	-	Vdc
Collector Cutoff Current (V <sub>CE</sub> = -30 Vdc, V <sub>EB(off)</sub> = -0.5 Vdc)		I <sub>CEX</sub>	-	-50	nAdc
Collector Cutoff Current $(V_{CB} = -50 \text{ Vdc}, I_E = 0)$ $(V_{CB} = -50 \text{ Vdc}, I_E = 0, T_A = 150^{\circ}\text{C})$		I <sub>CBO</sub>	-	-0.01 -10	μAdc
Emitter Cutoff Current (V <sub>EB</sub> = -3.0 Vdc)		I <sub>EBO</sub>	-	-10	nAdc
Collector Cutoff Current (V <sub>CE</sub> = -10 V)		I <sub>CEO</sub>	-	-10	nAdc
Base Cutoff Current (V <sub>CE</sub> = -30 Vdc, V <sub>EB(off)</sub> = -0.5 Vdc)		I <sub>BEX</sub>	-	-50	nAdc
ON CHARACTERISTICS				11	l.
DC Current Gain $ \begin{array}{l} (I_C = -0.1 \text{ mAdc, } V_{CE} = -10 \text{ Vdc}) \\ (I_C = -1.0 \text{ mAdc, } V_{CE} = -10 \text{ Vdc}) \\ (I_C = -10 \text{ mAdc, } V_{CE} = -10 \text{ Vdc}) \\ (I_C = -150 \text{ mAdc, } V_{CE} = -10 \text{ Vdc}) \\ (I_C = -500 \text{ mAdc, } V_{CE} = -10 \text{ Vdc}) \end{array} (\text{Note } C = -10 \text{ Vdc}) $		h <sub>FE</sub>	75 100 100 100 50	- - - 300	-
Collector-Emitter Saturation Voltage (Note 1 $(I_C = -150 \text{ mAdc}, I_B = -15 \text{ mAdc})$ $(I_C = -500 \text{ mAdc}, I_B = -50 \text{ mAdc})$	)	V <sub>CE(sat)</sub>	- -	-0.4 -1.6	Vdc
Base-Emitter Saturation Voltage (Note 1) (I <sub>C</sub> = -150 mAdc, I <sub>B</sub> = -15 mAdc) (I <sub>C</sub> = -500 mAdc, I <sub>B</sub> = -50 mAdc)		V <sub>BE(sat)</sub>	- -	-1.3 -2.6	Vdc
SMALL-SIGNAL CHARACTERISTICS					
Current-Gain - Bandwidth Product (Notes 1 (I <sub>C</sub> = -50 mAdc, V <sub>CE</sub> = -20 Vdc, f = 100 l		f <sub>T</sub>	200	-	MHz
Output Capacitance (V <sub>CB</sub> = -10 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)		C <sub>obo</sub>	-	8.0	pF
Input Capacitance (V <sub>EB</sub> = -2.0 Vdc, I <sub>C</sub> = 0, f = 1.0 MHz)	C <sub>ibo</sub>	-	30	pF	
SWITCHING CHARACTERISTICS					
Turn-On Time		t <sub>on</sub>	-	50	ns
Delay Time	$(V_{CC} = -30 \text{ Vdc}, I_{C} = -150 \text{ mAdc},$ $I_{B1} = -15 \text{ mAdc})$ (Figures 1 and 5)	t <sub>d</sub>	-	10	ns
Rise Time	. <sub>D1</sub> = 15 117 (85) (Figures 1 and 9)	t <sub>r</sub>	-	40	ns
Turn-Off Time		t <sub>off</sub>	-	110	ns
Storage Time	$(V_{CC} = -6.0 \text{ Vdc}, I_C = -150 \text{ mAdc}, I_{B1} = I_{B2} = -15 \text{ mAdc})$ (Figure 2)	ts	-	80	ns
Fall Time		t <sub>f</sub>	-	30	ns

<sup>1.</sup> Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%. 2. f<sub>T</sub> is defined as the frequency at which  $|h_{fe}|$  extrapolates to unity.

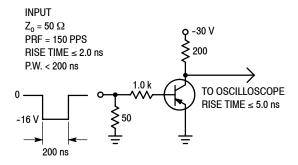


Figure 1. Delay and Rise Time Test Circuit

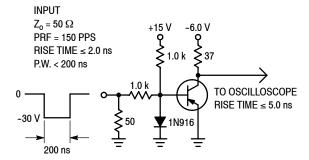


Figure 2. Storage and Fall Time Test Circuit

## **TYPICAL CHARACTERISTICS**

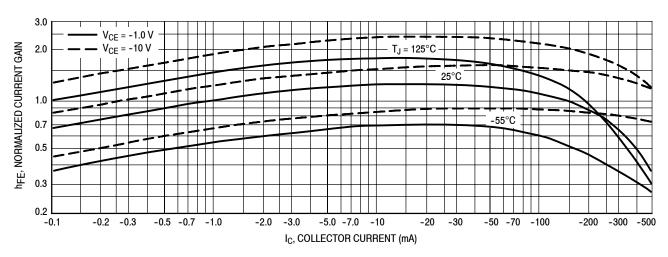


Figure 3. DC Current Gain

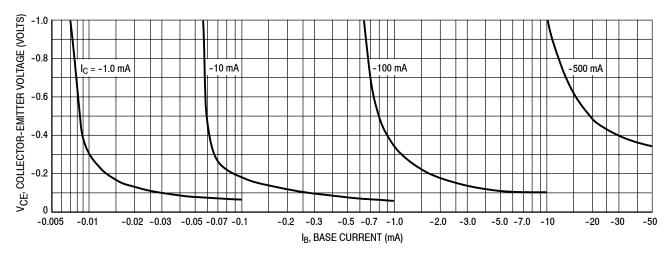


Figure 4. Collector Saturation Region

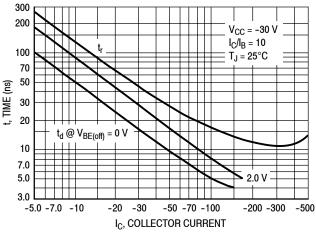


Figure 5. Turn-On Time

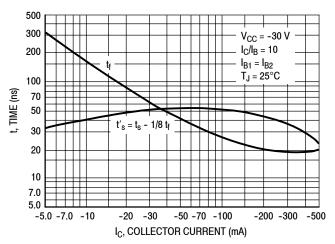


Figure 6. Turn-Off Time

# TYPICAL SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE

 $V_{CE}$  = 10 Vdc,  $T_A$  = 25°C

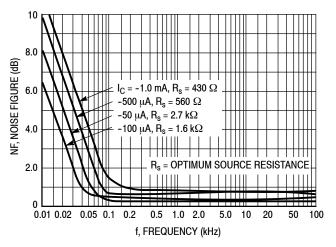


Figure 7. Frequency Effects

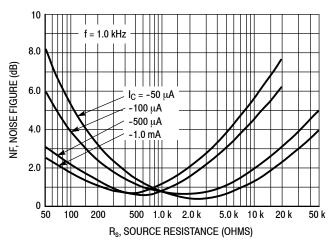


Figure 8. Source Resistance Effects

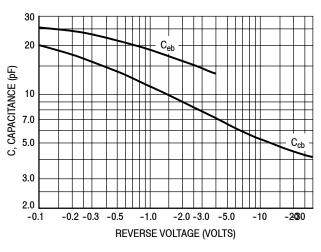


Figure 9. Capacitances

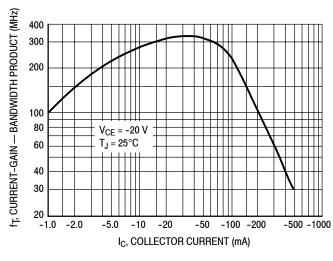


Figure 10. Current-Gain - Bandwidth Product

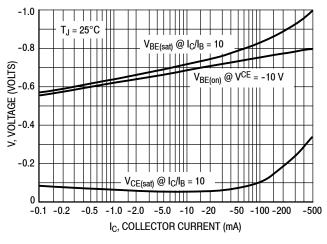


Figure 11. "On" Voltage

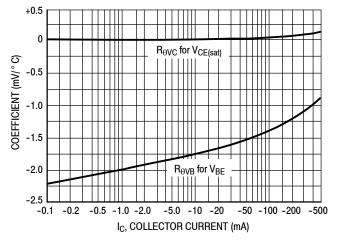
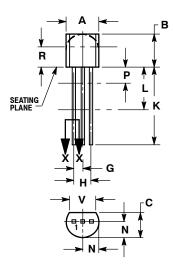


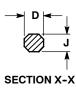
Figure 12. Temperature Coefficients

#### PACKAGE DIMENSIONS

TO-92 (TO-226) CASE 29-11 ISSUE AM



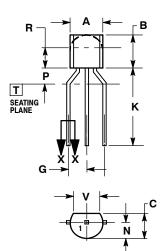
STRAIGHT LEAD **BULK PACK** 



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- CONTOUR OF PACKAGE BEYOND DIMENSION R
- IS UNCONTROLLED.
  LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
N	0.080	0.105	2.04	2.66
P		0.100		2.54
R	0.115		2.93	
V	0.135		3.43	



**BENT LEAD TAPE & REEL** AMMO PACK



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
  CONTOUR OF PACKAGE BEYOND
  DIMENSION R IS UNCONTROLLED.
  LEAD DIMENSION IS UNCONTROLLED IN P
- AND BEYOND DIMENSION K MINIMUM

	MILLIMETERS		
DIM	MIN MAX		
Α	4.45	5.20	
В	4.32	5.33	
С	3.18	4.19	
D	0.40	0.54	
G	2.40	2.80	
7	0.39	0.50	
K	12.70		
N	2.04	2.66	
P	1.50	4.00	
R	2.93		
٧	3.43		

STYLE 17:

PIN 1. COLLECTOR

BASE

**EMITTER** 

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